

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ0909NS	**Issued**	25. January 2018
MA#	MA001250068		
Package	PG-TSDSON-8-1	**Weight***	35.88 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.531	1.48	1.48	14794	14794
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		66	
	non noble metal	zinc	7440-66-6	0.009	0.03		264	
	non noble metal	iron	7439-89-6	0.189	0.53		5278	
	non noble metal	copper	7440-50-8	7.689	21.43	22.00	214328	219936
wire	non noble metal	copper	7440-50-8	0.039	0.11	0.11	1097	1097
encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1055	
	plastics	epoxy resin	-	1.950	5.44		54354	
	inorganic material	silicondioxide	60676-86-0	16.943	47.21	52.76	472296	527705
leadfinish	non noble metal	tin	7440-31-5	0.370	1.03	1.03	10316	10316
plating	noble metal	silver	7440-22-4	0.081	0.23	0.23	2252	2252
solder	non noble metal	tin	7440-31-5	0.017	0.05		475	
	noble metal	silver	7440-22-4	0.021	0.06		593	
	non noble metal	lead	7439-92-1	0.813	2.27	2.38	22667	23735
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33	
	non noble metal	zinc	7440-66-6	0.005	0.01		131	
	non noble metal	iron	7439-89-6	0.094	0.26		2620	
	non noble metal	copper	7440-50-8	3.816	10.64	10.91	106369	109153
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		109	
	non noble metal	iron	7439-89-6	0.078	0.22		2184	
	non noble metal	copper	7440-50-8	3.182	8.87	9.10	88692	91012
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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